



Material Content Data Sheet



Sales Product Name	BAT 64-04W H6327			Issued		29. August 2013		
MA#	MA001094592							
Package	PG-SOT323-3-1			Weight*		5.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15	
	noble metal	gold	7440-57-5	0.009	0.15		1506	
	inorganic material	silicon	7440-21-3	0.051	0.86	1.01	8574	10095
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.88	44.06	438681	440532
wire	non noble metal	copper	7440-50-8	0.006	0.09	0.09	937	937
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5245	
	plastics	epoxy resin	-	0.673	11.28		112770	
	inorganic material	silicondioxide	60676-86-0	2.425	40.65	52.45	406498	524513
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22245	22245
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1678	1678
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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